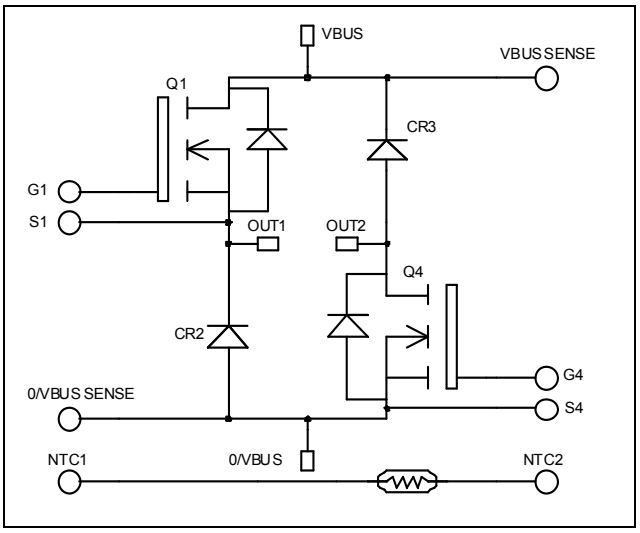
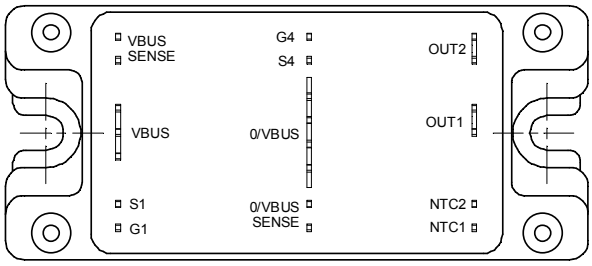
Asymmetrical - Bridge MOSFET Power Module

V_{DSS} = 200V
R_{DSon} = 20mΩ max @ Tj = 25°C
I_D = 89A @ Tc = 25°C





Application

- Welding converters
- Switched Mode Power Supplies
- Switched Reluctance Motor Drives

Features

- Power MOS 7® MOSFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		200	V
I_D	Continuous Drain Current	T_c = 25°C	89	A
		T_c = 80°C	66	
I_{DM}	Pulsed Drain current		356	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		20	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	357	W
I_{AR}	Avalanche current (repetitive and non repetitive)		89	A
E_{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		2500	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
BV_{DSS}	Drain - Source Breakdown Voltage	V_{GS} = 0V, I_D = 250µA		200			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS} = 200V	T_j = 25°C			100	µA
		V_{GS} = 0V, V_{DS} = 160V	T_j = 125°C			500	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 44.5A				20	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 2.5mA		3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V				±100	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		6850		pF
C_{oss}	Output Capacitance			2180		
C_{rss}	Reverse Transfer Capacitance			97		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 100V I_D = 75A		112		nC
Q_{gs}	Gate – Source Charge			43		
Q_{gd}	Gate – Drain Charge			47		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 133V I_D = 75A R_G = 5Ω		28		ns
T_r	Rise Time			56		
$T_{d(off)}$	Turn-off Delay Time			81		
T_f	Fall Time			99		
E_{on}	Turn-on Switching Energy ❶	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 75A, R_G = 5Ω		463		µJ
E_{off}	Turn-off Switching Energy ❷			455		
E_{on}	Turn-on Switching Energy ❶	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 75A, R_G = 5Ω		608		µJ
E_{off}	Turn-off Switching Energy ❷			531		

Diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle	T_c = 90°C		100		A
V_F	Diode Forward Voltage	I_F = 100A			1	1.1	V
		I_F = 200A			1.4		
		I_F = 100A	T_j = 125°C		0.9		
t_{rr}	Reverse Recovery Time	I_F = 100A V_R = 133V di/dt = 200A/µs	T_j = 25°C		60		ns
			T_j = 125°C		110		
Q_{rr}	Reverse Recovery Charge	I_F = 100A V_R = 133V di/dt = 200A/µs	T_j = 25°C		200		nC
			T_j = 125°C		840		

❶ E_{on} includes diode reverse recovery.
❷ In accordance with JEDEC standard JESD24-1.

Thermal and package characteristics

Symbol	*Characteristic*			*Min*	*Typ*	*Max*	*Unit*
R_{thJC}	Junction to Case		Transistor			0.35	°C/W
			Diode			0.6	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, I isol<1mA, 50/60Hz			2500			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5			4.7	N.m
Wt	Package Weight					160	g

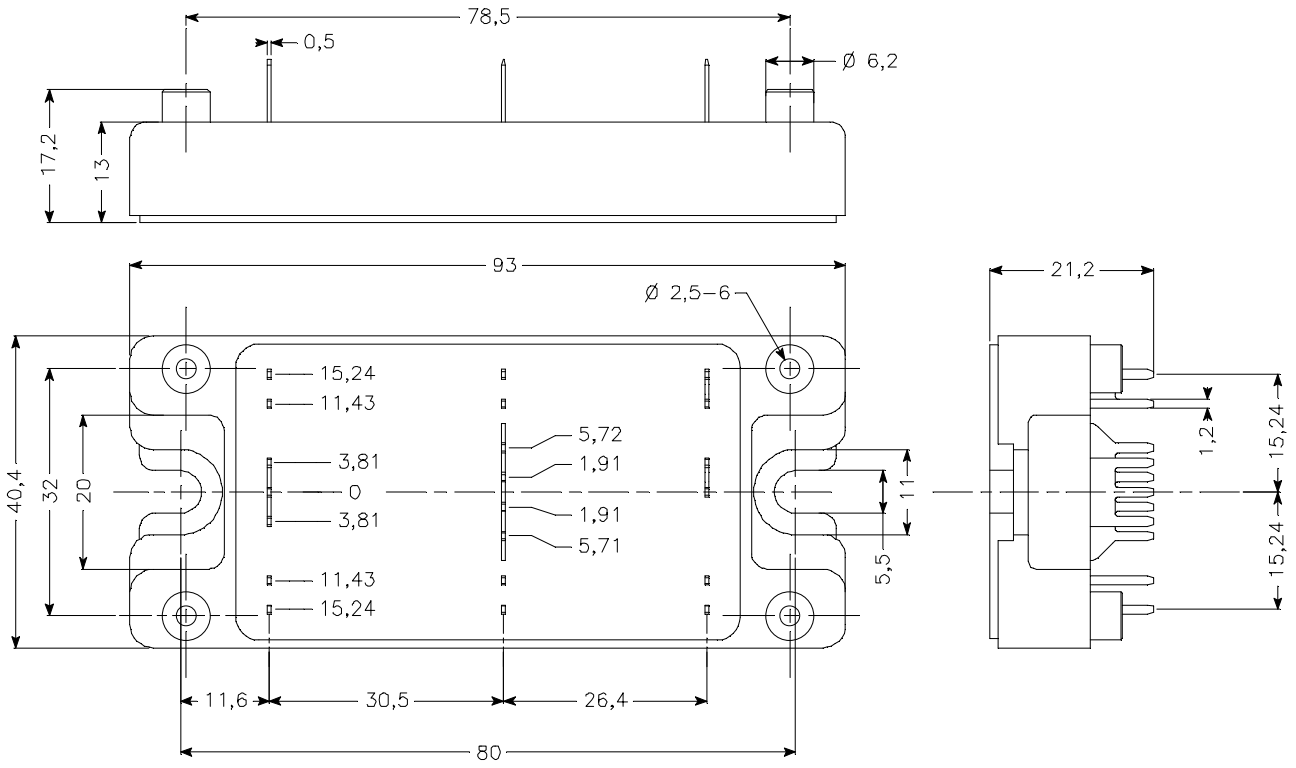
Temperature sensor NTC

Symbol	*Characteristic*	*Min*	*Typ*	*Max*	*Unit*
R_{25}	Resistance @ 25°C		68		kΩ
$B_{25/85}$	T_{25} = 298.16 K		4080		K

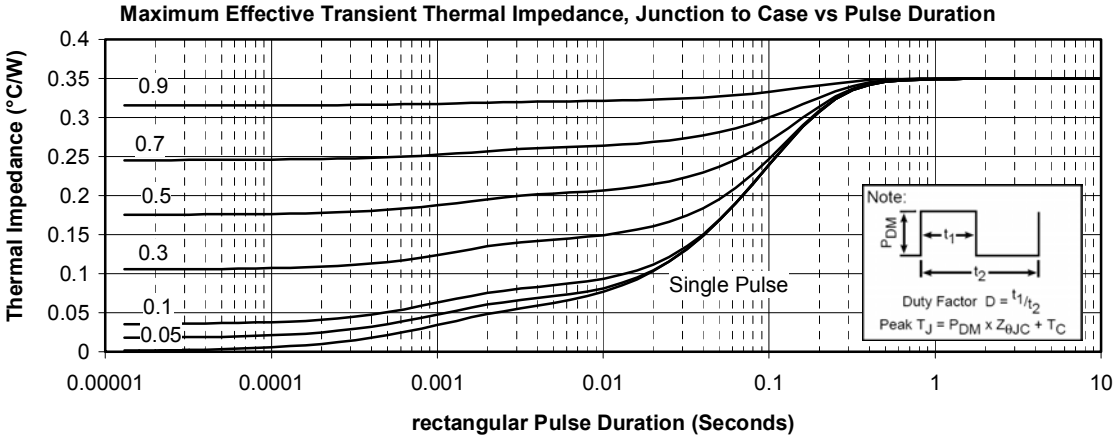
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

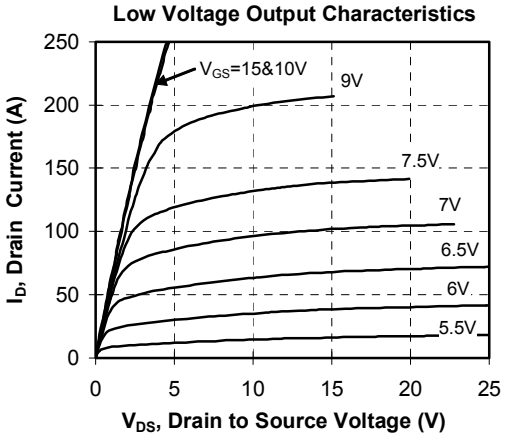
T: Thermistor temperature
R_T: Thermistor value at T

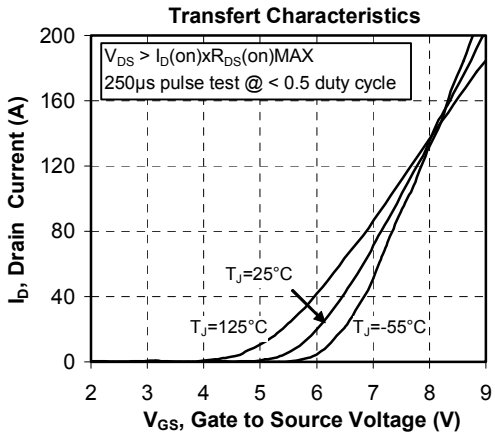
Package outline

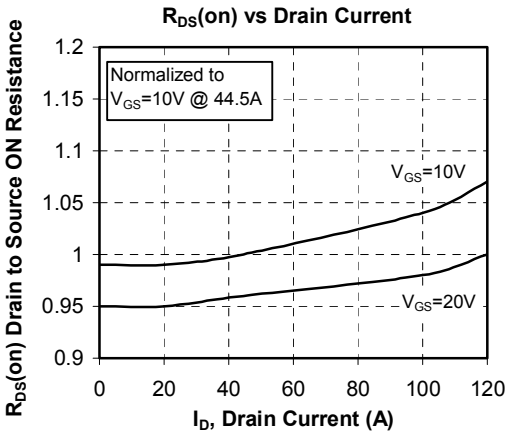


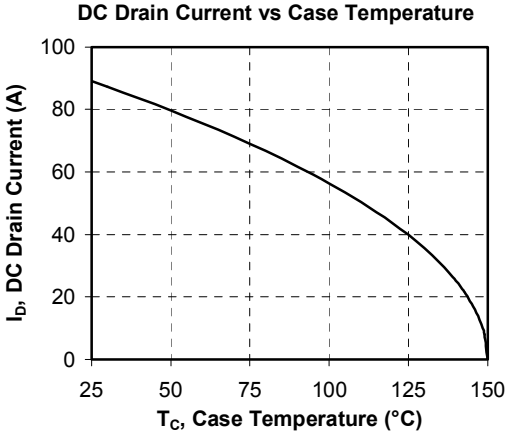
Typical Performance Curve

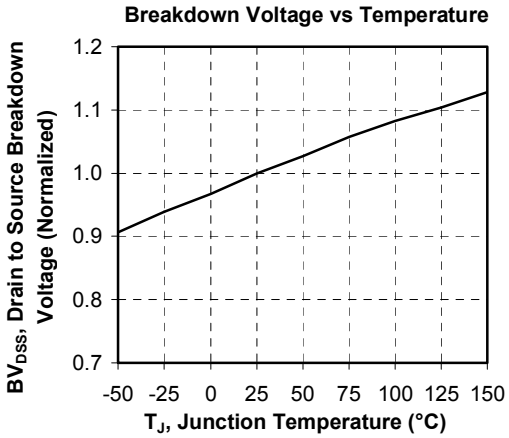


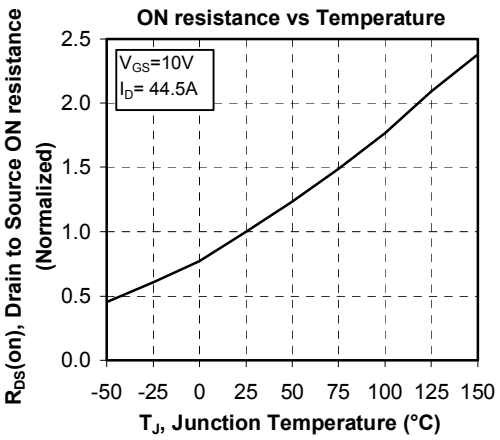


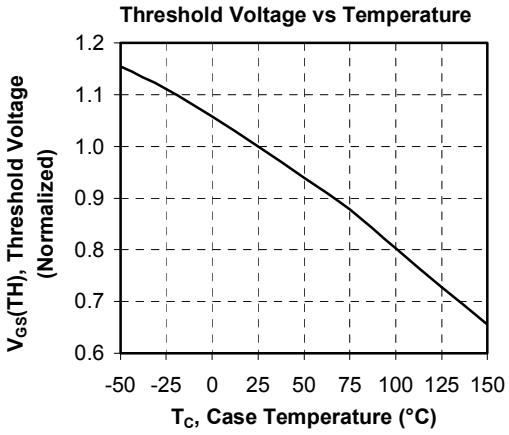


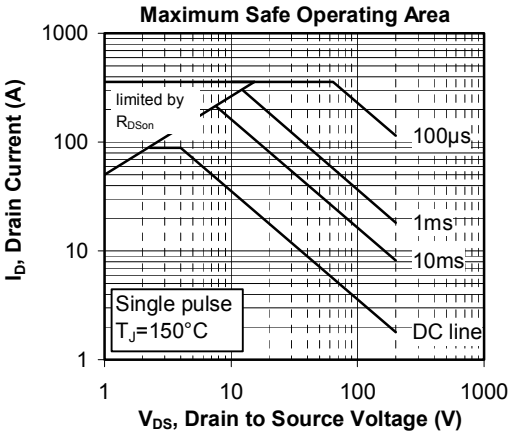


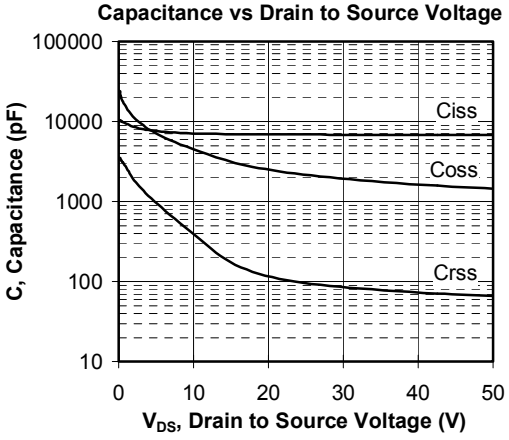


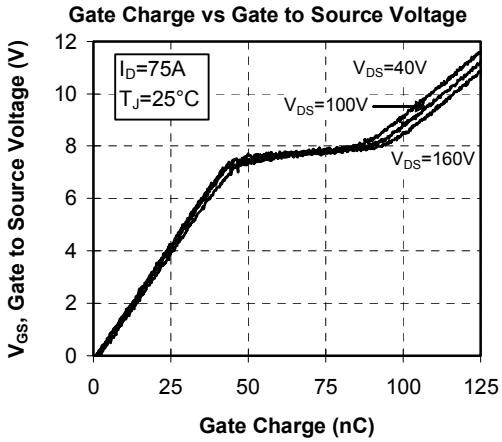

Breakdown Voltage vs Temperature
BVDSS, Drain to Source Breakdown Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)


ON resistance vs Temperature
RDS(on), Drain to Source ON resistance (Normalized)
VGS=10V
ID= 44.5A
2.5
2.0
1.5
1.0
0.5
0.0
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)

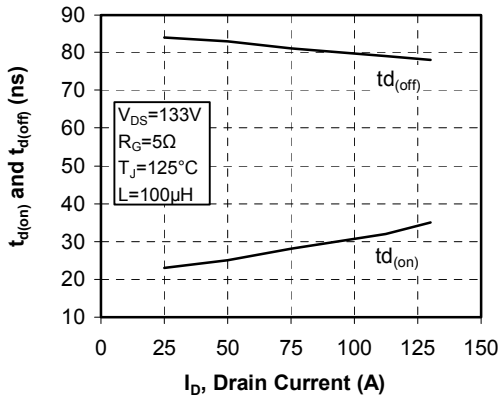

Threshold Voltage vs Temperature
VGS(TH), Threshold Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
0.6
-50 -25 0 25 50 75 100 125 150
TC, Case Temperature (°C)


Maximum Safe Operating Area
ID, Drain Current (A)
1000
100
10
1
limited by RDSon
100µs
1ms
10ms
Single pulse
TJ=150°C
DC line
1 10 100 1000
VDS, Drain to Source Voltage (V)

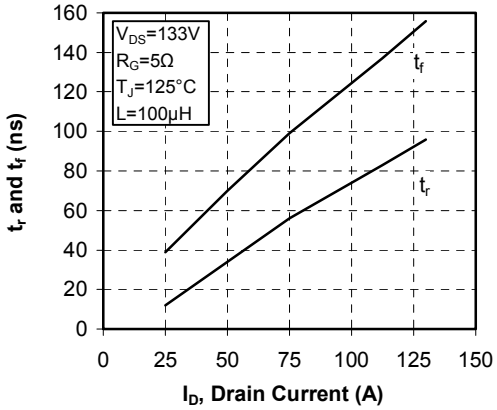

Capacitance vs Drain to Source Voltage
C, Capacitance (pF)
100000
10000
1000
100
10
Ciss
Coss
Crss
0 10 20 30 40 50
VDS, Drain to Source Voltage (V)


Gate Charge vs Gate to Source Voltage
VGS, Gate to Source Voltage (V)
12
10
8
6
4
2
0
ID=75A
TJ=25°C
VDS=40V
VDS=100V
VDS=160V
0 25 50 75 100 125
Gate Charge (nC)

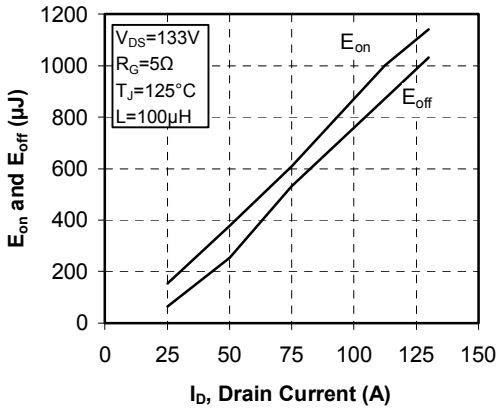
Delay Times vs Current



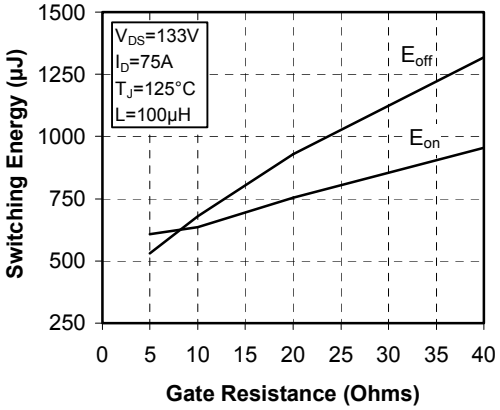
Rise and Fall times vs Current



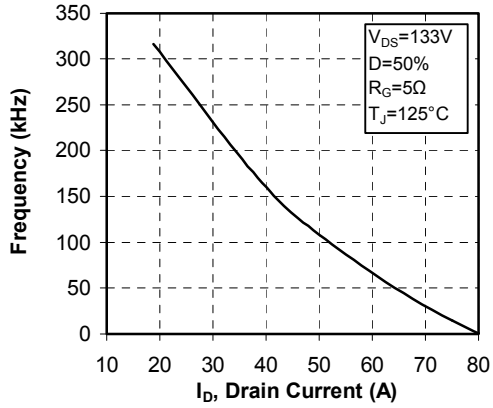
Switching Energy vs Current



Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage